MA2S7840G

Silicon epitaxial planar type

For super high speed switching For small current rectification

Features

- High-density mounting is possible
- Forward current (Average) $I_{F(AV)} = 100 \text{ mA}$ rectification is possible
- Optimum for high frequency rectification because of its short reverse recovery time t_{rr}
- \bullet Low forward voltage V_{F} and good rectification efficiency

Parameter	Symbol	Rating	Unit				
Reverse voltage	V _R	30	V				
Repetitive peak reverse voltage	V _{RRM}	30	V				
Forward current (Average)	I _{F(AV)}	100	mA				
Peak forward current	I_{FM}	300	mA				
Non-repetitive peak forward surge current *	I _{FSM}	1	А				
Junction temperature	Tj	125	°C				
Storage temperature	T _{stg}	-55 to +125	°C				

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Package

- Code
- SSMini2-F4
- Pin Name
- 1: Anode
- 2: Cathode
- Marking Symbol: C

Note) *: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

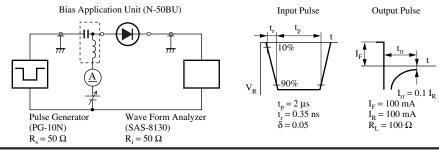
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V _F	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I _R	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$		20		pF
Reverse recovery time *	t _{rr}	$I_F = I_R = 100 \text{ mA}$		2.0		ns
		$I_{rr} = 0.1 I_R$, $R_L = 100 \Omega$				

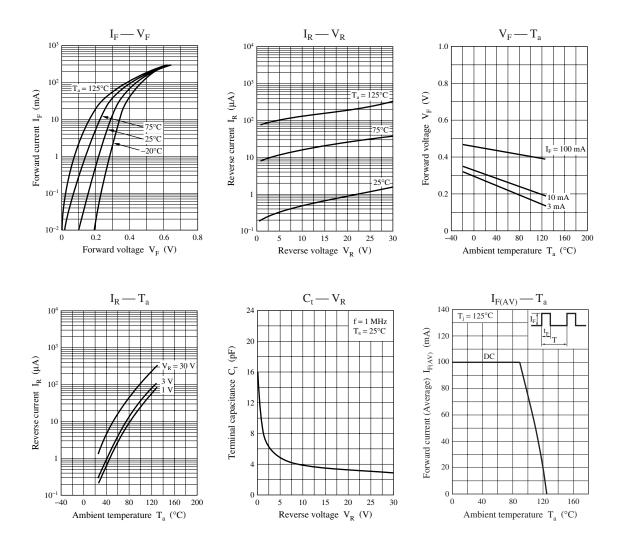
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

- 3. Absolute frequency of input and output is 250 MHz.
- 4. *: t_{rr} measurement circuit



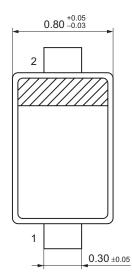
Panasonic

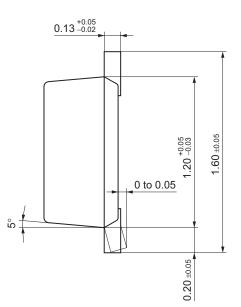


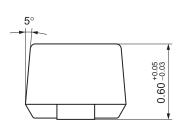
Panasonic

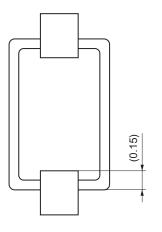
SSMini2-F4

Unit: mm









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